



PROCESS CHANGE NOTIFICATION PCN0407

UFBGA 88 PACKAGE SUBSTRATE CHANGE

Change Description:

The substrate for the 88 Lead Ultra FineLine BGA® package assembled by Sharp will change from polyimide tape to glass epoxy FR4. This change does not affect form, fit, or function.

Reason for Change:

The polyimide tape is being discontinued.

Products Affected:

This substrate change affects the configuration devices, EPC16UC88 and EPC16UC88AA.

Product Traceability and Transition Dates:

This change will be implemented beginning August 2004. Beginning with the top mark date code of 0431, customers may receive the UFBGA package constructed using the glass epoxy FR4 substrate.

Contact:

Preliminary qualification data is available upon request. For more information, please contact your local Altera® sales representative or the Altera Customer Quality Engineering Department at (408) 544-7821.